

Title (en)

PROCESS FOR PACKAGING A PRESSURE-SENSITIVE ELECTRONIC CIRCUIT IN A PROTECTIVE HOUSING SEALED ALL AROUND

Title (de)

VERFAHREN ZUM VERPACKEN EINER DRUCKKEMPFINDLICHEN ELEKTRONISCHEN SCHALTUNG MIT EINER ALLSEITIG ABDICHTENDEN SCHUTZUMHÄUSUNG

Title (fr)

PROCEDE DE CONDITIONNEMENT D'UN CIRCUIT ELECTRONIQUE SENSIBLE A LA PRESSION DANS UN BOITIER PROTECTEUR ETANCHE DE TOUS LES COTES

Publication

**EP 0835523 A1 19980415 (DE)**

Application

**EP 96917348 A 19960614**

Priority

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Abstract (en)

[origin: WO9702601A1] A process is disclosed for packaging a pressure-sensitive electronic circuit in a protective housing sealed all around. A plastic housing open on one side is injection-moulded around a printed circuit board (1) which is then equipped with electronic components. The thus obtained unit (5) is placed in a second injection mould that may be composed of two halves that can be successively and individually filled with injection moulding plastic material. A preform (6) that closes the opening of the plastic housing (4) at a certain distance from the circuit is injection moulded into the first half of the injection mould. The second half of the injection mould is then moved nearer to the first half and finished form (7) is injection moulded therein so as to seal the plastic housing (4) closed by the injection moulded preform (6).

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